United States Patent [19]

Hasegawa et al.

[11] **Patent Number: Des. 318,461**

[45] **Date of Patent: *** Jul. 23, 1991**

[54] **SEMI-CONDUCTOR MOUNTING SUBSTRATE**

[75] Inventors: **Terutomi Hasegawa**, Ogaki; **Nobumichi Goto**, Seki, both of Japan

[73] Assignee: **Ibiden Co., Ltd.**, Ogaki, Japan

[*] Notice: The portion of the term of this patent subsequent to Oct. 24, 2003 has been disclaimed.

[**] Term: **14 Years**

[21] Appl. No.: **181,252**

[22] Filed: **Apr. 13, 1988**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/12, 20, 99; 361/401, 403, 404, 405; 357/70, 72, 74, 80; 174/52.4; 437/209

[56] **References Cited**

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Electronics, p. 7, Feb. 24, 1986 by Fujitsu Microelectronics, Inc.

Electronic Design, p. 7, dtd 10–16–86, NRC 1C package pictured thereon.

Electronic Design, p. 190, dtd 10–16–86, Disc Controll pictured thereon.

Electronics, p. 131, dtd 8–7–86, CMOS chip pictured thereon.

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Attorney, Agent, or Firm—Lorusso & Loud

[57] **CLAIM**

The ornamental design for a semi-conductor mounting substrate, as shown.

DESCRIPTION

FIG. **1** is a top perspective view of a semi-conductor mounting substrate showing our new design;

FIG. **2** is a bottom perspective view thereof;

FIG. **3** is a right side elevational view thereof;

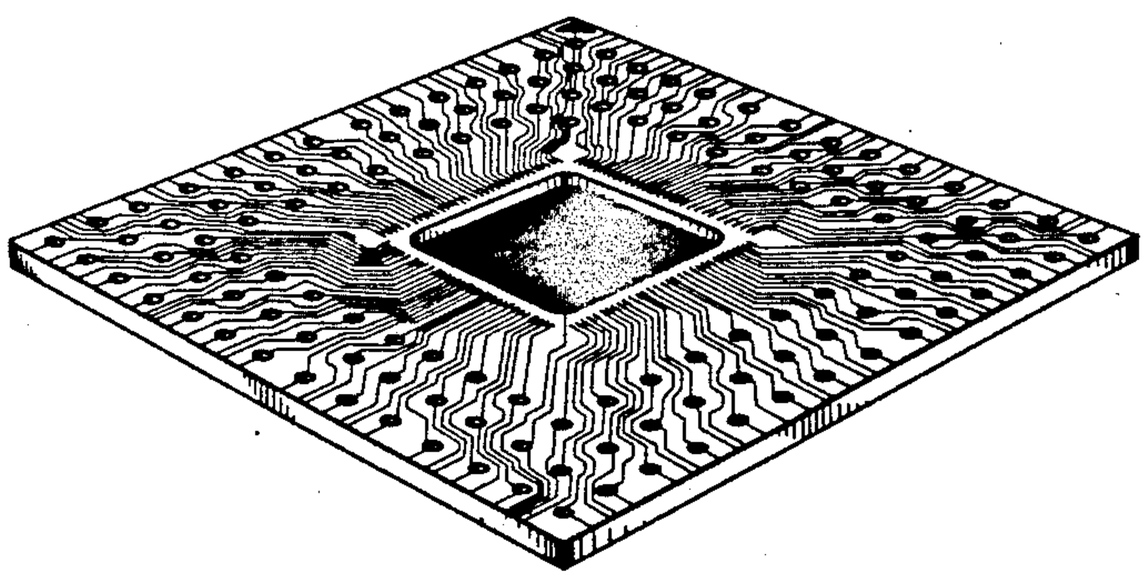
FIG. **4** is a left side elevational view thereof;

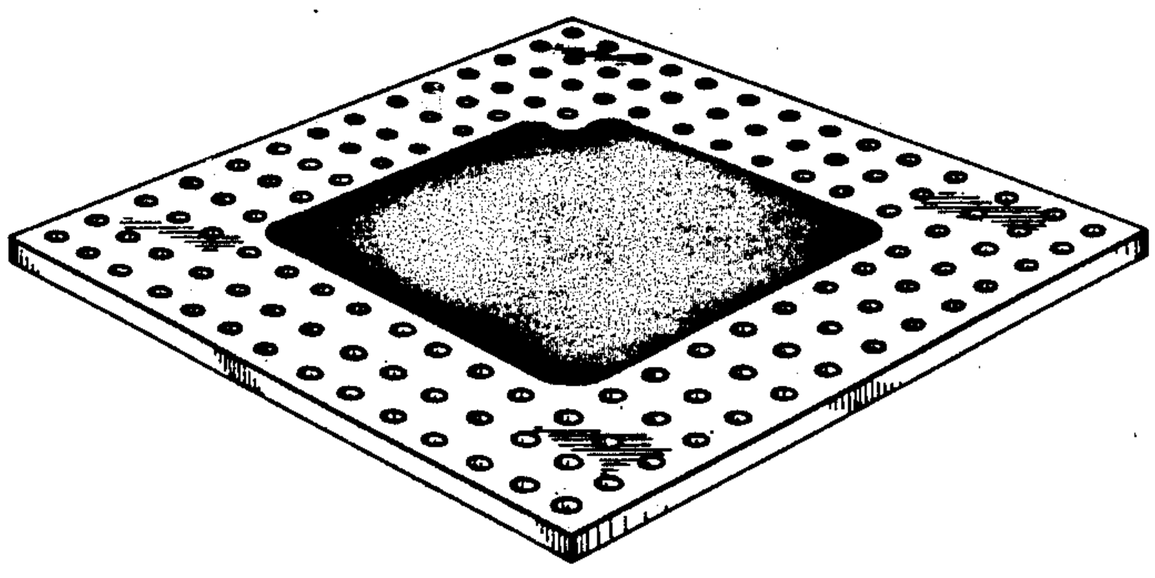
FIG. **5** is a rear elevational view thereof;

FIG. **6** is a front elevational view thereof;

FIG. **7** is a top plan view thereof; and

FIG. **8** is a bottom plan view thereof.





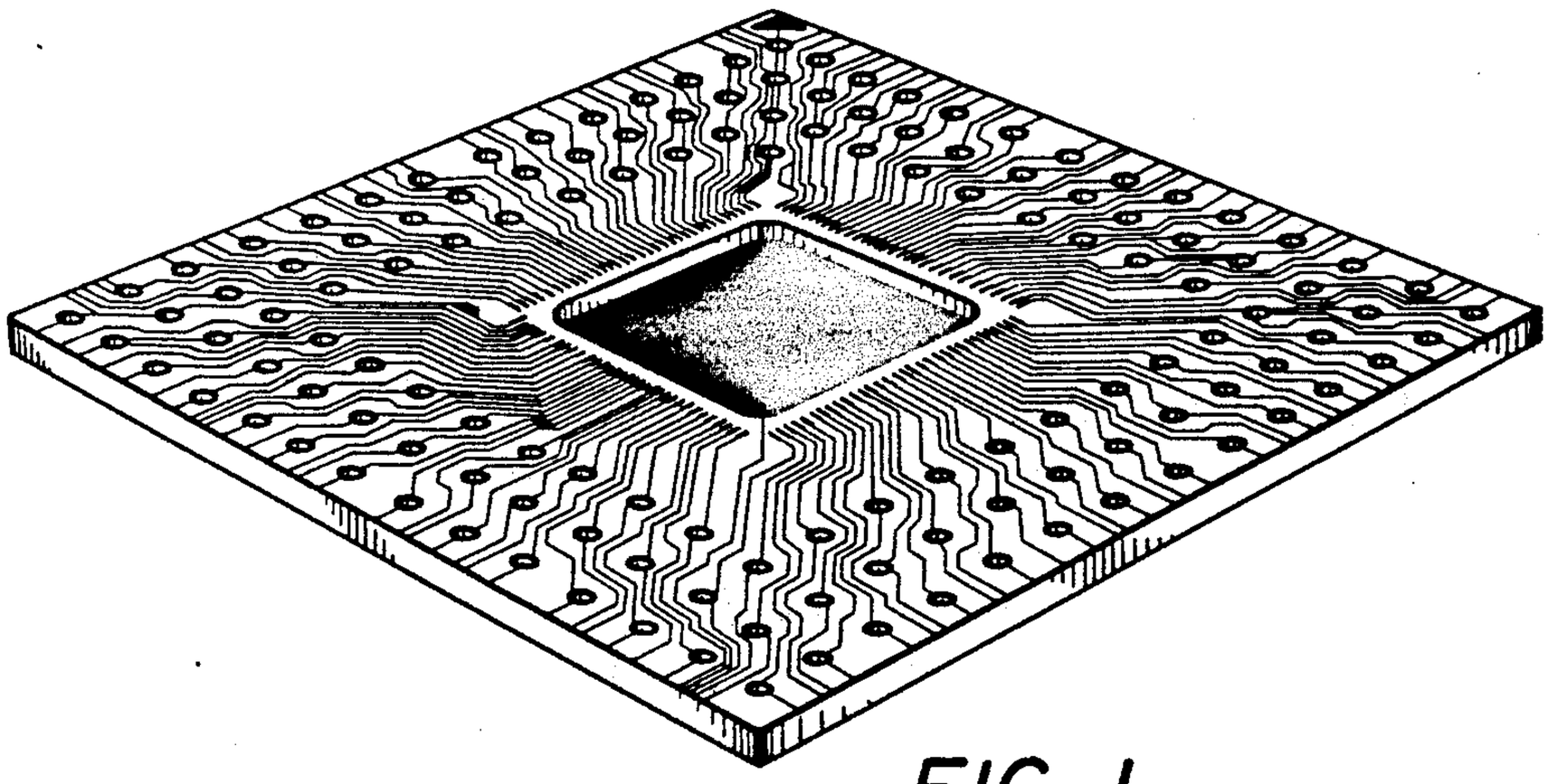


FIG. 1

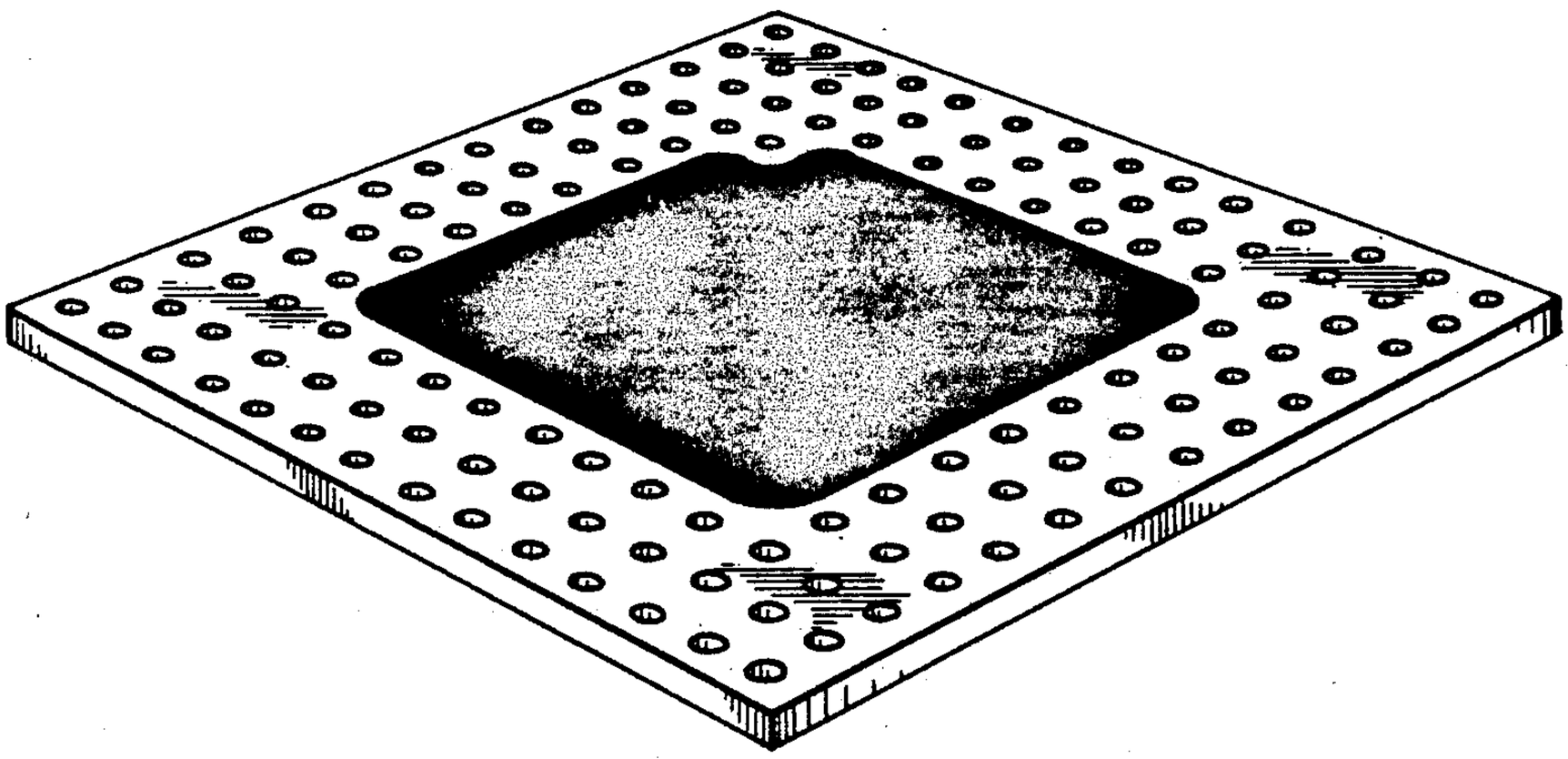


FIG. 2

FIG. 3

FIG. 4

FIG. 5

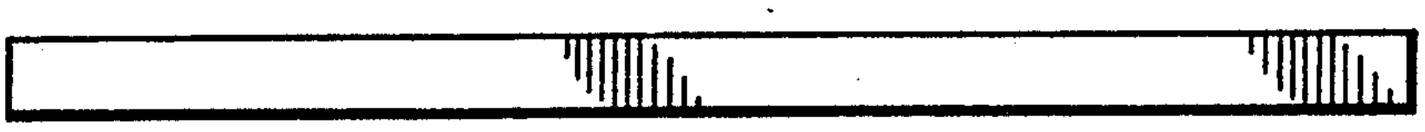


FIG. 6

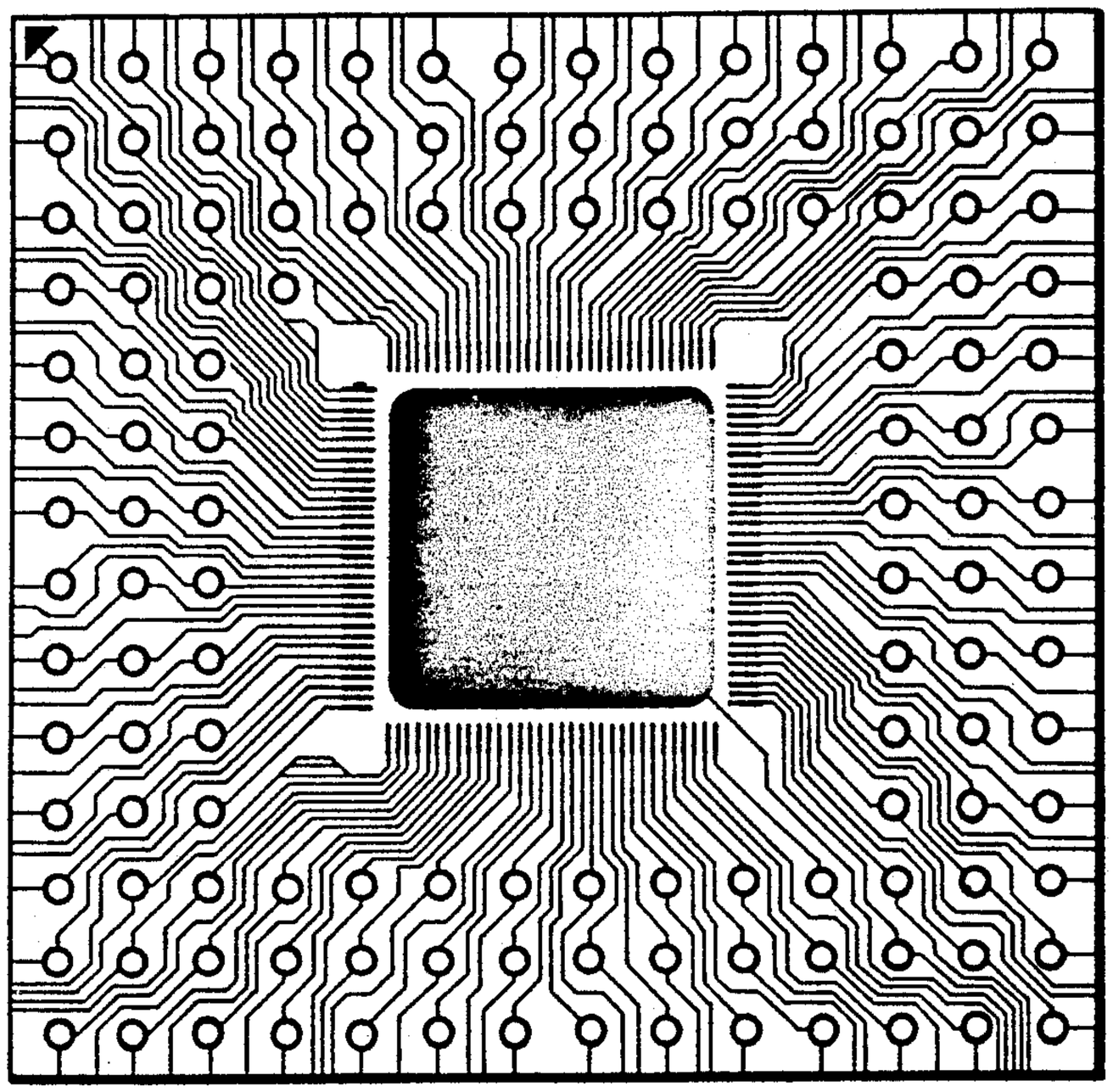


FIG. 7

FIG. 8

UNITED STATES PATENT AND TRADEMARK OFFICE

CERTIFICATE OF CORRECTION

PATENT NO. : Des. 318,461

DATED : July 23, 1991

INVENTOR(S) : Hasegawa et al.

It is certified that error appears in the above—identified patent and that said Letters Patent is hereby corrected as shown below:

In Col. 1, line 6, the "[*] Notice:" section should be delete in its entirety.

Signed and Sealed this

Fifteenth Day of June, 1993

Attest:

MICHAEL K. KIRK

Attesting Officer

Acting Commissioner of Patents and Trademarks